

Assignment-3

Q) My PC:

i) System Description:

- AMD Ryzen 5 1600
- Number of Cores : 6
- Number of Threads : 12
- Base Clock Speed : 3.2 GHz
- PSU : 550 W

ii) Main Memory Specification:

- 8 GB DDR4 Ram
- Speed : 3200 MHz
- Type : DDR4
- Slots : 2 (Dual-channel)

iii) Storage Details:

- 512 GB NVMe SSD

- 1 TB HDD

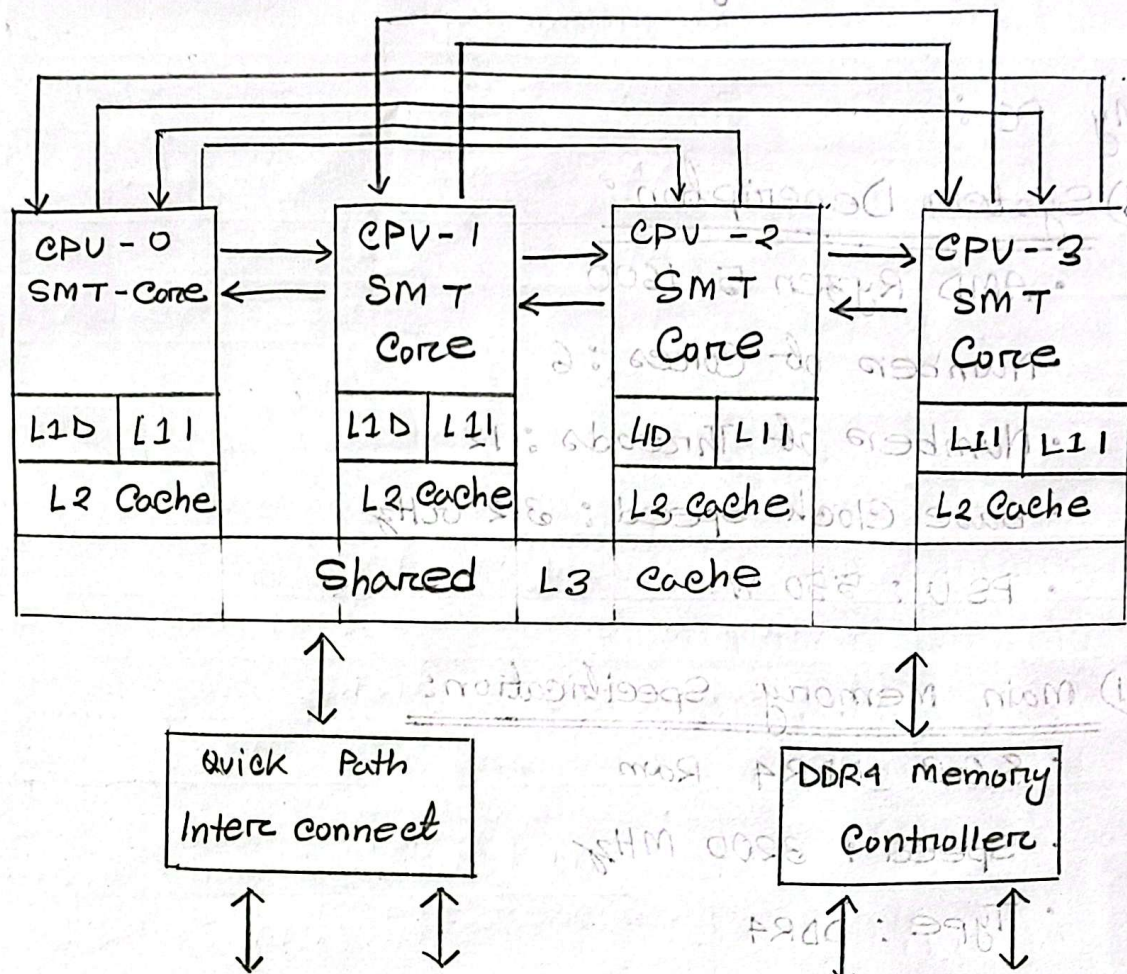
- SSD:

Read speed : up to 3200 MB/s

Write speed : up to 2700 MB/s

II) Process Details:

1) Block Diagram:



Ref: wiki.chipbuse.com

2. Instruction Set Related Specification:

- ISA: x86-64 (also known as x64)
- Supports SIMD Extensions: SSE4, AVX, AVX2
- Instruction Fetch, Decode, Execute Memory Access, write back stages

3. Specification:

- Pipeline Details: 14 stage pipeline with throughput.
- Multiple Issue Details: Supports Hyper Threading Technology (SMT)

Cache Memory Details:

- L1 cache - 32KB Per core
- L2 cache - 256 KB Per core

→ L3 cache: 12 MB Shared

- Bus: Direct Media Interface (DMI) 3.0
- Interrupt: Advanced Programmable Interrupt Controller
- I/O: PCI 3.0, USB 3.1
- DMA: Integrated Directed Memory Access controllers

b) My Mobile Phone: (OPPO)

i) System Description:

- Processor: MediaTek Dimensity 8100 - max
- Number of cores: 8
- Config: Octa-core (4x Cortex-A78 at 2.85 GHz + 4x Cortex-A55 at 2.0 GHz)
- Manufacturing Process: 5nm

2. Main memory specification:

- 8 GB LPDDR5 RAM
- Speed: 2750 MHz

Type: LPDDR5

3. Storage Details:

- 256 GB UFS 3.0 -

• Read Speed: Up to 2100 MB/s

• Write Speed: Up to 1200 MB/s

ii) Processor Details:

1) Block Diagram:

Snapdragon 865		
Prime Core (Cortex - A77) 2.84 GHz	Performance Cores (x3) (Cortex - A77) 2.42 GHz	Efficiency Cores (Cortex - A55) 1.8 GHz
L3 cache (4MB shared)		
Adreno 650 GPU (Graphics Processor Unit)		
Hexagon 698 DSP		
Spectra 480 ISP		
Memory Controller (LPDDR5)		
AI Engine		
Modem (x55 5G Modem)		
Connectivity (Wifi, Bluetooth)		
I/O Interfaces (USB 3.1)		

Ref: www.qualcomm.com

2. Instruction related Info:

- ISA ARM v8-A
- Supports SIMD Extensions: NEON
- Instruction Fetch, Decode, Execute, Memory Access and write back stages.

3. Specifications:

- Pipelining Details: Out of order execution with a 10 stage pipeline.
- Multiple Issue Details: Supports big.Little architecture for power efficiency
- Cache memory Details:
 - L1 cache: 64 kB (I) + 64 kB (D) Per core
 - L2 cache: 1 MB (A77) + 512 kB (A55)
 - L3 cache: 4 MB shared

• Bus : AXI , AHB

• Interrupt : Generic Interrupt Controller

• I/O : USB 3.1 , PCIe 3.0

• DMA : Integrated DMA controller

c) Recent & Popular Embedded microcontroller:

STM32 F407 VGT6

i) System Description :

1. Processor Specification :

• Core : ARM Cortex - M4

• Clock Speed : 168 MHz

• Flash memory : 1 MB

• SRAM : 192 KB

2. Main memory Specification :

• Internal SRAM : 192 KB

• External memory Interface : FSMC for

external SRAM , PSRAM , NOR , NAND memory

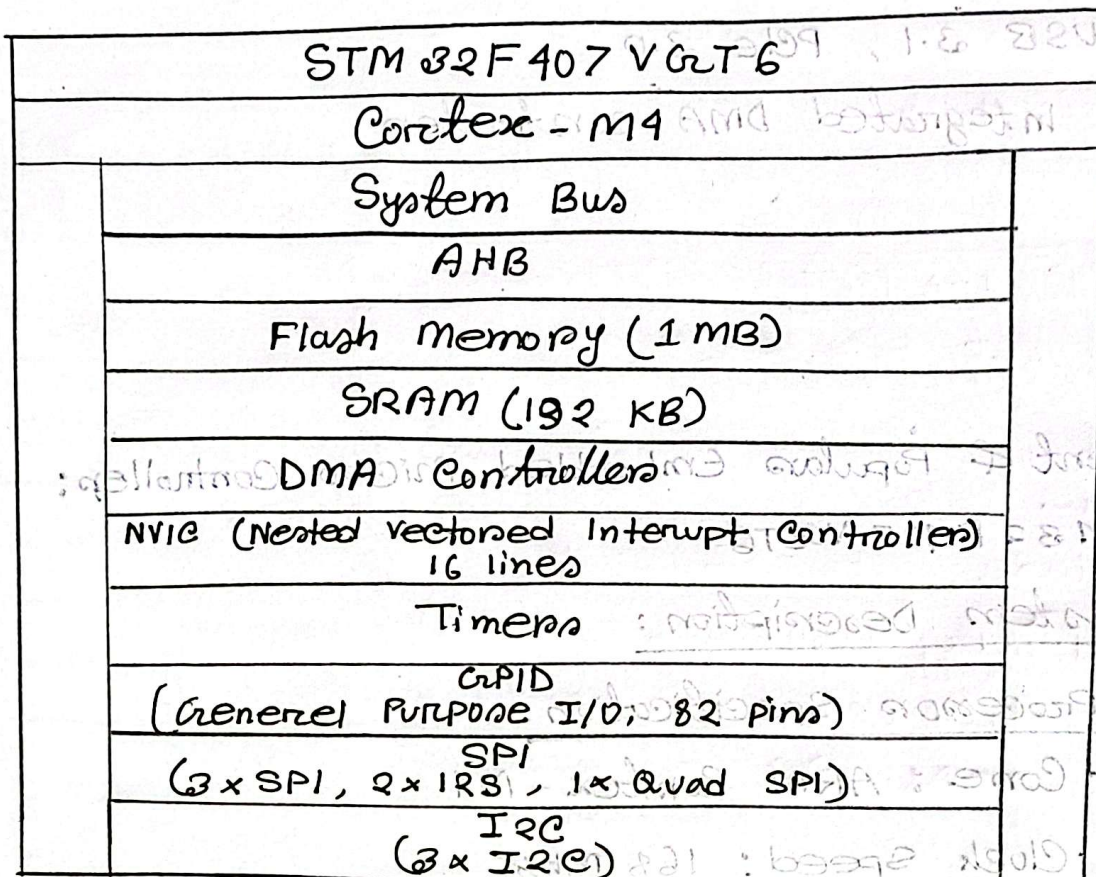
3. Storage Details :

• Embedded Flash : 1 MB

• External storage : Support for external
NAND/NOR flash via FSMC

ii) Processor Details:

1. Block Diagram:



Ref: researchgate.com

2. Instruction Set Related Info:

- ISA: ARM V7-M (Thumb-2)
- Supports SIMD Extensions: ARM DSP extensions.
- Instruction fetch, Decode, execute memory Access and write back stages.

3. Specifications:

- Pipelining Details: 3 stage (fetch, decode, execute)
- Multiple Issue details: Single issue
- Cache Memory details -
 - Instruction Cache: 4KB
 - Data Cache: 4KB

- I/O: GPIO, UART, SPI, I2C, CAN, USB
- DMA: 16-stream DMA controllers.

(iii) Application and Programming?

Application:

- Industrial Control system
- Medical device
- Consumer electronics

Setup i → Install STM32CubeIDE

→ Connect STM32407VGT6 to the PC via ST-link

Example Code:

```
#include "stm32f4xx.h"

void delay (uint32_t count) {
    while (count --) {
        __NOP();
    }
}

int main (void) {
    RCC → AHB1ENR |= RCC_AHB1ENR_GPIOGEN;
    GPIOE → MODER |= GPIO_MODER_13_0;
    while (1) {
        GPIOE → ODR = GPIO_ODR_ODR_13;
        delay (5000000);
    }
}
```